



Material Content Data Sheet



Sales Product Name		BSZ110N06NS3 G		Issued		20. July 2018		
MA#		MA000522552						
Package		PG-TSDSON-8-2		Weight*		39.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.296	3.25	3.25	32537	32537
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53	
	non noble metal	zinc	7440-66-6	0.008	0.02		210	
	non noble metal	iron	7439-89-6	0.168	0.42		4209	
wire	non noble metal	copper	7440-50-8	6.808	17.09	17.54	170910	175382
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	897	897
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.09		944
encapsulation	plastics	epoxy resin	-	1.937	4.86		48640	
	inorganic material	silicondioxide	60676-86-0	16.835	42.29	47.24	422646	472230
leadfinish	non noble metal	tin	7440-31-5	0.392	0.98	0.98	9841	9841
plating	noble metal	silver	7440-22-4	0.963	2.42	2.42	24166	24166
solder	noble metal	silver	7440-22-4	0.037	0.09		922	
	non noble metal	tin	7440-31-5	0.029	0.07		738	
	non noble metal	lead	7439-92-1	1.404	3.52	3.68	35239	36899
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.086	0.22		2165	
	non noble metal	copper	7440-50-8	3.501	8.79	9.02	87898	90198
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47	
	non noble metal	zinc	7440-66-6	0.008	0.02		189	
	non noble metal	iron	7439-89-6	0.151	0.38		3788	
	non noble metal	copper	7440-50-8	6.127	15.38	15.78	153826	157850
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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